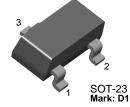


BCW31

NPN General Purpose Amplifier

- This device is designed for general purpose applications at collector currents to 300mA.
- Sourced from process 10.



1. Base 2. Emitter 3. Collector

Absolute Maximum Ratings * T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CEO}	Collector-Emitter Voltage	32	V
V _{CBO}	Collector-Base Voltage	32	V
V _{EBO}	Emitter-Base Voltage	5.0	V
I _C	Collector current (DC)	500	mA
T _J , T _{sta}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- NOTES:

 1) These ratings are based on a maximum junction temperature of 150 degrees C.

 2) These are state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charact	eristics		•	•	•	•
V _{(BR)CBO}	Collector-Base Breakdown Voltage	I _C = 2.0mA, I _B = 0	32			V
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	$I_{C} = 10\mu A, I_{B} = 0$	32			V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_C = 10\mu A, I_C = 0$	5.0			V
I _{CBO}	Collector Cutoff Current	$V_{CB} = 32V, I_{E} = 0$ $V_{CB} = 32V, I_{E} = 0, T_{A} = 100^{\circ}C$			100 10	nA μA
On Charact	eristics			•		
h _{FE}	DC Current Gain	I _C = 2.0mA, V _{CE} = 5.0V	110		220	
V _{CE(sat)}	Collector-Emitter Saturation Voltage	$I_C = 10 \text{mA}, I_B = 0.5 \text{mA}$			0.25	V
V _{BE(on)}	Base-Emitter On Voltage	I _C = 2.0mA, V _{CE} = 5.0V	0.55		0.7	V
Small Signa	al Characteristics		•			
f _T	Current Gain Bandwidth Product	$I_C = 2.0 \text{mA}, V_{CE} = 5.0 \text{V}$ f = 35MHz	200			
C _{obo}	Output Capacitance	$V_{CB} = 10V, I_E = 0, f = 1.0MHz$			4.0	pF
NF	Noise Figure	$I_C = 0.2\text{mA}, V_{CE} = 5.0\text{V}$ $R_S = 2.0\text{k}\Omega, f = 1.0\text{kHz}$ $B_W = 200\text{Hz}$			10	dB

Thermal Characteristics $T_A=25$ °C unless otherwise noted

Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient 357 °C/V		°C/W
Device mounted on FR-4PCB 40mm × 40mm × 1.5mm			

Typical Characteristics

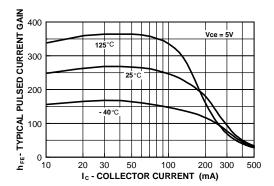


Figure 1. Typical Pulsed Current Gain vs Collector Current

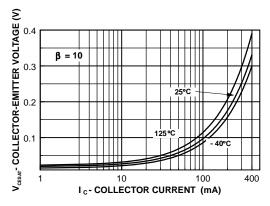


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

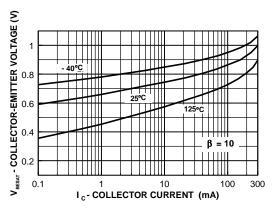


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

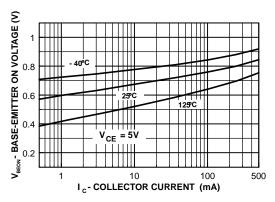


Figure 4. Base-Emitter On Voltage vs Collector Current

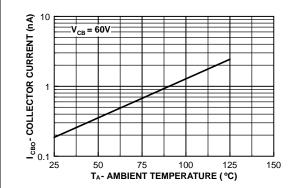


Figure 5. Collector-Cutoff Current vs Ambient Temperature

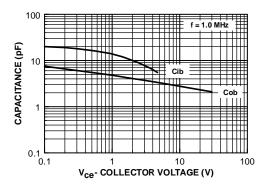


Figure 6. Input and Outtput Capacitance vs Reverse Voltage

Rev. B1, August 2002

Typical Characteristics (Continued)

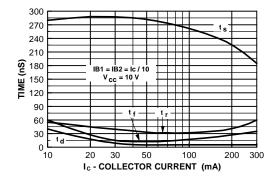


Figure 7. Switching Times vs Collector Current

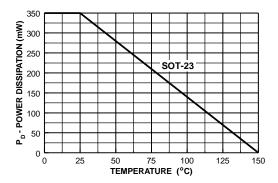
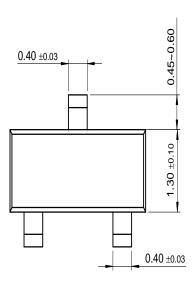
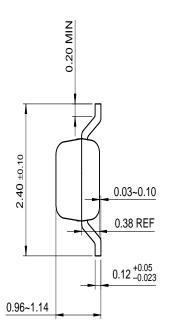


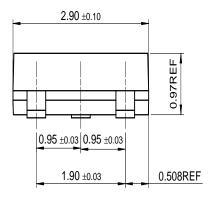
Figure 8. Power Dissipation vs Ambient Temperature

Package Dimensions

SOT-23







Dimensions in Millimeters

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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E ² CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I^2C^{TM}	OCX^{TM}	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET [®]
The Power Franchise™		OPTOLOGIC [®]	SILENT SWITCHER®	VCX^{TM}
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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